



CATCH-U-DNA General Meeting 3rd December 2017, Tel Aviv, Israel



WP1. Acoustic wave devices and measurement control unit

Objectives and current results

Outline



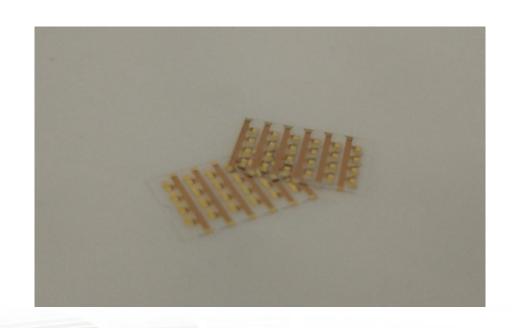
- 1. Objectives
- 2. Results
- 3. Next steps



Chip containing an array of TSBAR sensors

Requirements

- Size < 6 cm2
- Cost < 2€ (mass production)
- Op. frequency between
 150 MHz and 2GHz





Measurement system

Requirements

- High resolution
- Stability in the ppt range
- Real time



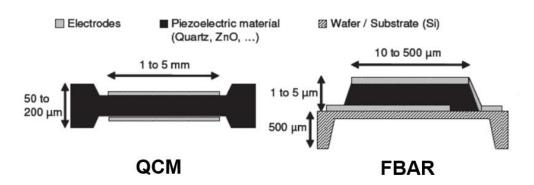




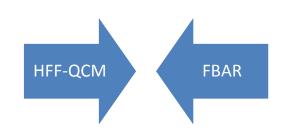








- Operating frequencies (100- 700 MHz)
- AT-cut quartz
- Integration capability (0.5 mm)
- High Q factor
- Low complexity
- Low cost



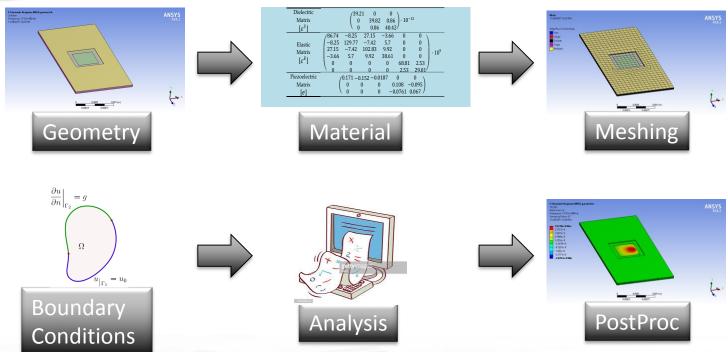
- Operating frequencies (1- 2 GHz)
- ZnO or AIN
- Integration capability (0.1 mm)
- CMOS standard
- Medium/High Complexity
- Low cost

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3D FEM MODELING



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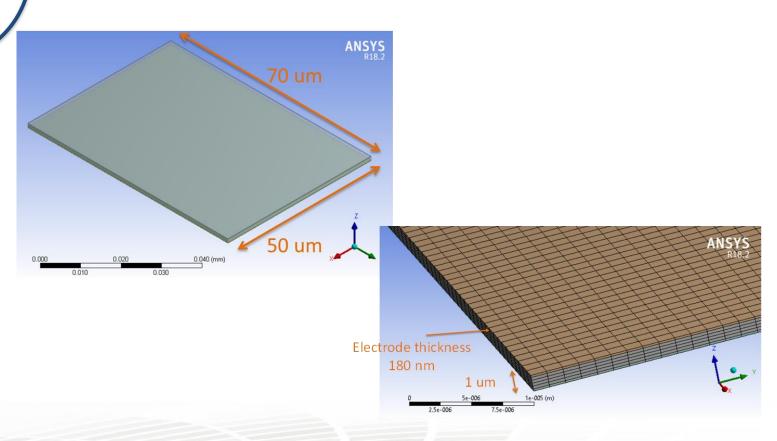
3D FEM MODELING





SENSOR DESIGN AND MODELING Task 1.1 (M1-M15)

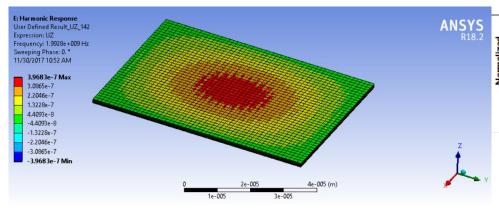
FBAR SENSOR MODELING

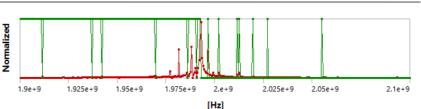




FBAR SENSOR MODELING

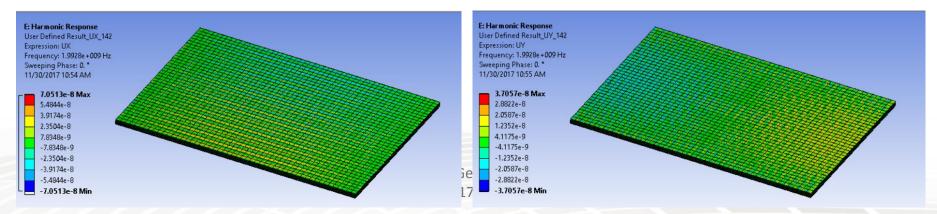
AlN substrate – Pt electrodes FBAR





AWSensors

Scientific Technology

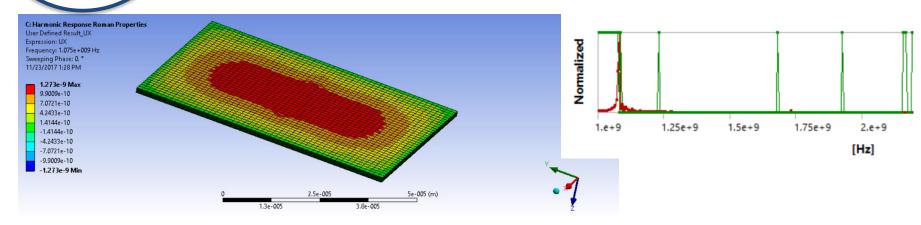


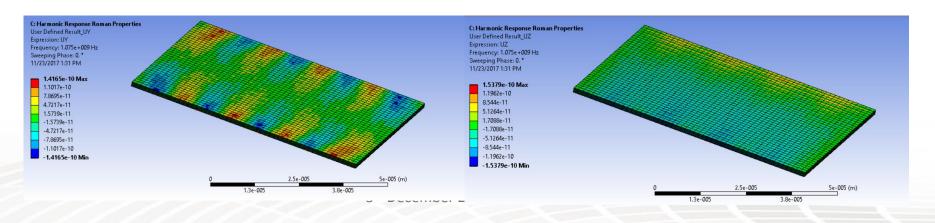


SENSOR
DESIGN AND
MODELING
Task 1.1
(M1-M15)

FBAR SENSOR MODELING

AlN substrate - Pt electrodes S-FBAR



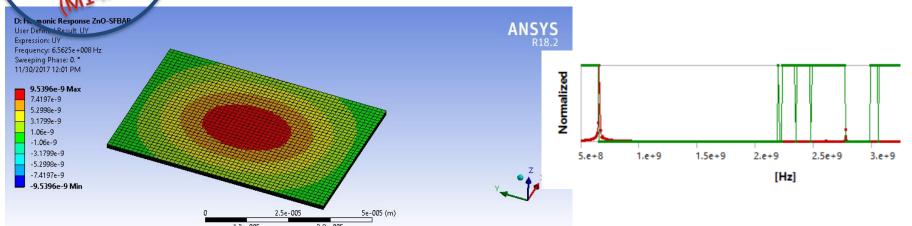


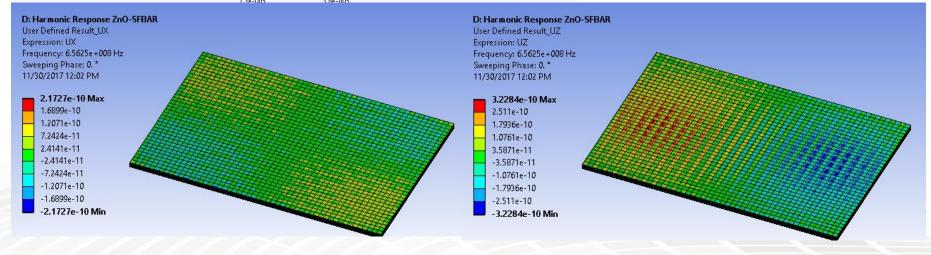




FBAR SENSOR MODELING

ZnO substrate – Pt electrodes S-FBAR

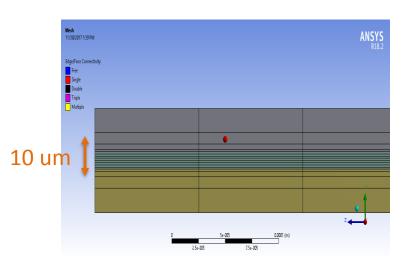


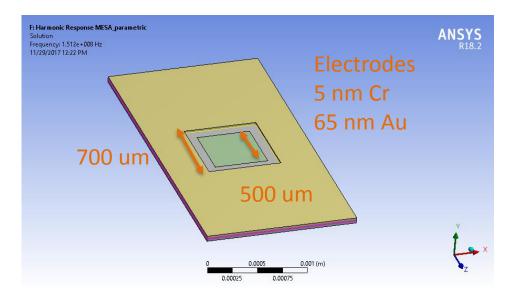


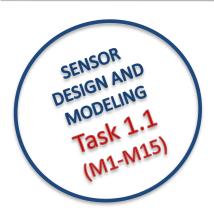




HFFQCM SENSOR MODELING



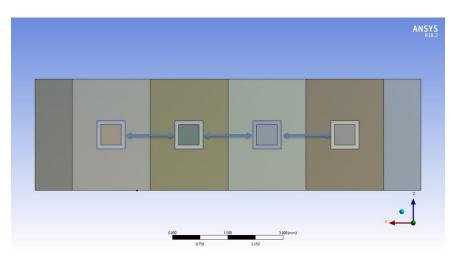




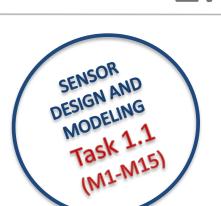


HFFQCM SENSOR MODELING

Array parametric study: Spacing



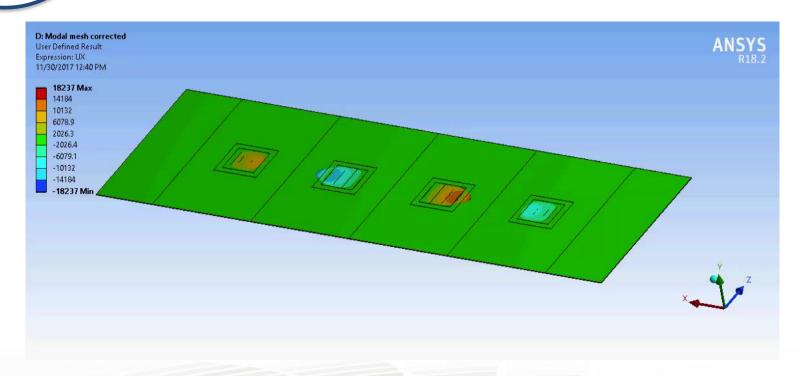
	DP0	DP1	DP2	DP3	DP4
Spacing (mm)	1.408	1.584	1.76	1.936	2.112





HFFQCM SENSOR MODELING

Modal Analysis

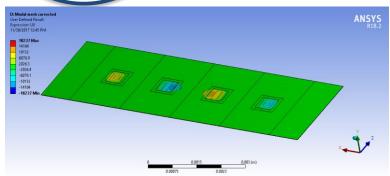


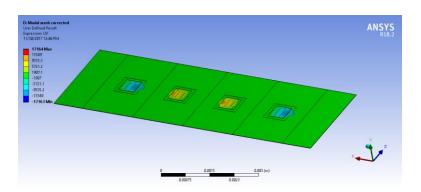


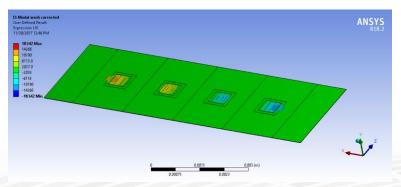
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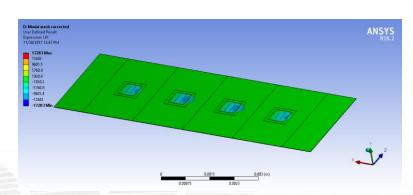
HFFQCM SENSOR MODELING

Modal Analysis









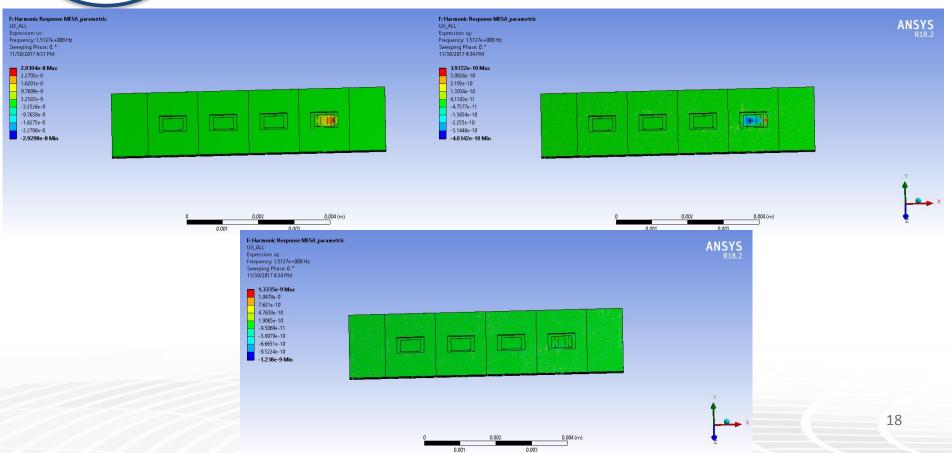
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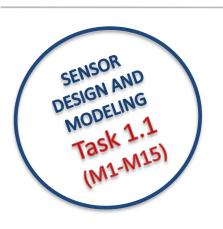




HFFQCM SENSOR MODELING

Harmonic Analysis

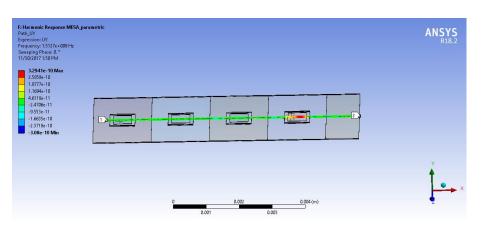


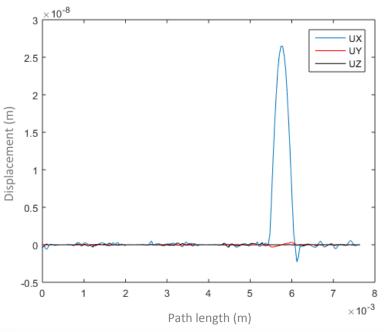


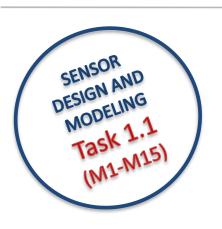


HFFQCM SENSOR MODELING

Harmonic Analysis



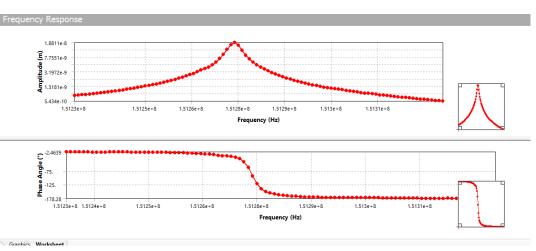


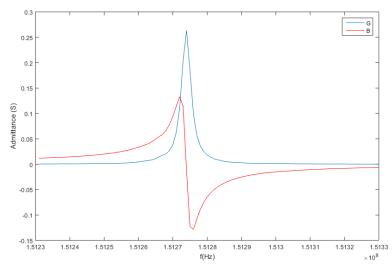




HFFQCM SENSOR MODELING

Harmonic Analysis









SENSOR FABRICATION PROCEDURE

Microfabrication process definition

Packaging process definition

Implementation

Characterization

Validation as a biosensor





SENSOR FABRICATION PROCEDURE

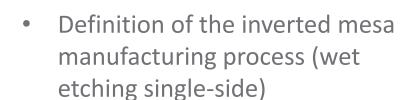
Microfabrication process definition

Packaging process definition

Implementation

Characterization

Validation as a biosensor



- Photomask tooling draft design
- Electrode Plating Mask tooling draft design





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Microfabrication process definition

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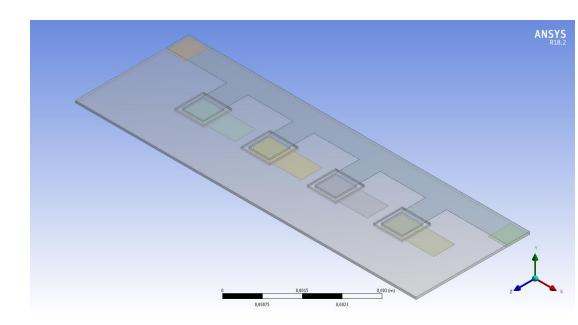
Electric interface design





FIRST PROTOTYPE

- Numerical Model Calibration (Damping)
- Manufacturing process validation
- uFluidic cell proof of concept
- Preliminary testing with biosamples



3. Next Steps





ONGOING WORK

- Multiphysics postprocessing to estimate insertion losses
 (S21) in sensor arrays
- Development of a more detailed S-FBAR model
- S-FBAR array design and model
- HFF-QCM array design optimization using parametric design techniques
- S-FBAR array design optimization using parametric design techniques
- S-FBAR vs. HFF-QCM Comparative analysis in terms of S and Q and interference

3. Next Steps





ONGOING WORK

- Implementation of the 4-sensor HFF-QCM array first prototype
- Development of the prototype packaging
- HFF-QCM prototype characterization

3. Next Steps





ONGOING WORK

- Development of the electrical/mechanical interface for HFF-QCM prototype
- Increasing frequency range (image frequency)
- Mixed (Tracking- Fixed frequency) characterization algorithm